


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	D68C*U708FB6	A	MU1A	2015-11-30
Amount	UoM	Unit type	ST ECOPACK Grade	
1925.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	15.9X11X3.5	36	gull wing	
Comment	Package: PowerSO 36 .430 BODY WIDTH, MD valid for CP:E-L6258EXTR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	D68C*U708FB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	18.376	mg	supplier	die	Silicon (Si)	7440-21-3		17.96	mg	977362	9330
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.103	mg	5605	54
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.058	mg	3156	30
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.242	mg	13169	126
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	54	1
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	163	2
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.009	mg	490	5
Leadframe	Copper & its alloys	1235.273	mg	supplier	alloy	Copper (Cu)	7440-50-8		1231.675	mg	997087	639831
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.567	mg	459	295
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.036	mg	839	538
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		1.995	mg	1615	1036
Soft solder	Solder	11.173	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	10.893	mg	974940	5659
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.168	mg	15036	87
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.112	mg	10024	58
Bonding wire	Other inorganic materials	1.762		supplier	wire	Gold (Au)	7440-57-5		1.744	mg	989784	906
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.011	mg	6243	6
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.005	mg	2838	3
Bonding wire				supplier	wire	Platinum (Pt)	7440-06-4		0.002	mg	1135	1
encapsulation	Other Organic Materials	652.47	mg	supplier	mold compound	Phenol Resin	205830-20-2		26.099	mg	40000	13558
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		19.574	mg	30000	10168
encapsulation				supplier	mold compound	epoxy resin	Proprietary		19.574	mg	30000	10168
encapsulation				supplier	mold compound	carbon black	1333-86-4		1.305	mg	2000	678
encapsulation				supplier	mold compound	silica vitreous	60676-86-0		585.918	mg	898000	304373
connections coating	Solder	5.946	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.946	mg	1000000	3089